



30V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)}$	I_D
30 V	19 mΩ	8 A

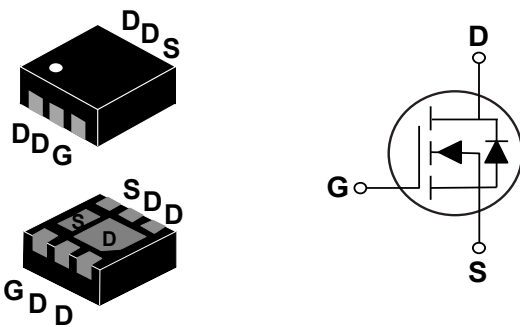
Features

- $R_{DS(ON)} \leq 19m\Omega @ V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

DFN2x2-6L Pin Configuration



Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current - Continuous ($T_A=25^\circ\text{C}$)	8	A
	Drain Current - Continuous ($T_A=70^\circ\text{C}$)	6.4	A
I_{DM}	Drain Current - Pulsed (NOTE 1)	32	A
P_D	Power Dissipation ($T_A=25^\circ\text{C}$)	2	W
	Power Dissipation - Derate above 25°C	16.1	mW/ $^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62	$^\circ\text{C}/\text{W}$

**30V N-Channel MOSFETs****Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	---	---	10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =4A	---	---	19	mΩ
		V _{GS} =4.5V, I _D =3A	---	---	27	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.6	2.5	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _S =2A	---	4	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _D =4A (NOTE 2、3)	---	5.2	---	nC
Q _{gs}	Gate-Source Charge		---	0.6	---	
Q _{gd}	Gate-Drain Charge		---	2	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =15V, V _{GS} =10V, R _G =6Ω, I _D =4A (NOTE 2、3)	---	2.8	---	ns
T _r	Rise Time		---	7.2	---	
T _{d(off)}	Turn-Off Delay Time		---	15.8	---	
T _f	Fall Time		---	4.6	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1MHz	---	490	---	pF
C _{oss}	Output Capacitance		---	80	---	
C _{rss}	Reverse Transfer Capacitance		---	55	---	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	2.2	---	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	8	A
I _{SM}	Pulsed Source Current		---	---	16	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time	V _R =30V, I _S =8A, di/dt=100A/us, T _J =25°C	---	130	---	ns
Q _{rr}	Reverse Recovery Charge		---	200	---	nC

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



Characteristics Curves

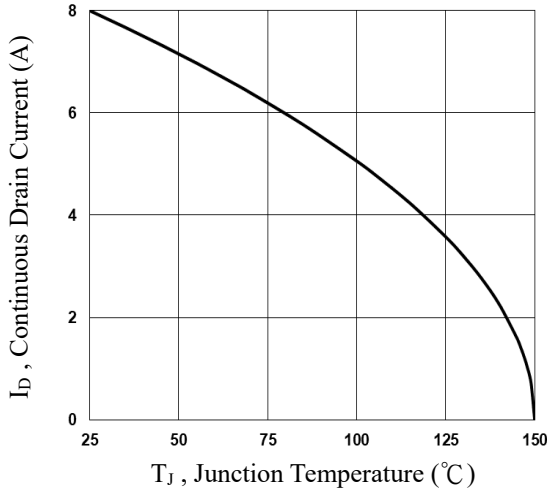


Fig.1 Continuous Drain Current vs. T_J

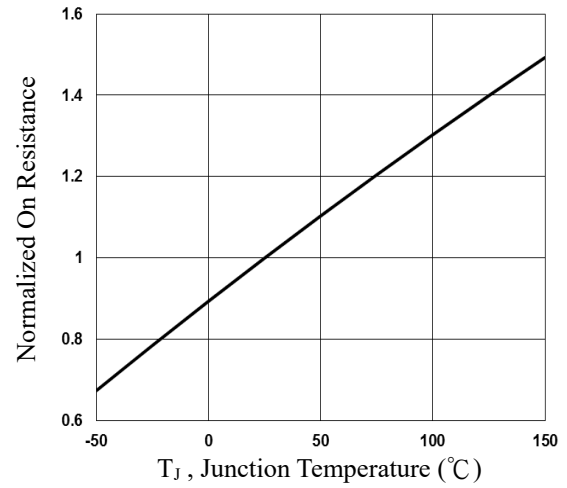


Fig.2 Normalized R_{DS(on)} vs. T_J

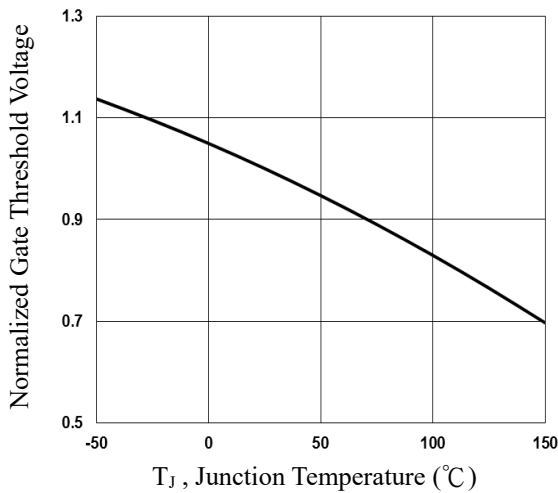


Fig.3 Normalized V_{th} vs. T_J

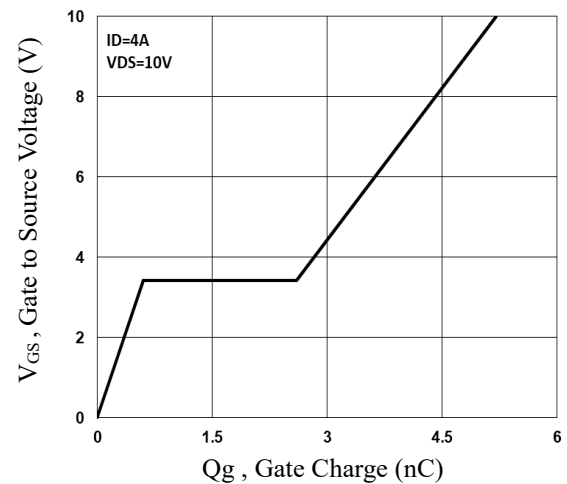


Fig.4 Gate Charge Waveform

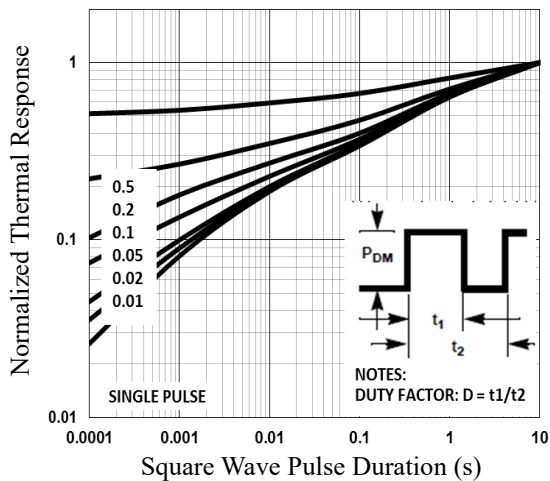


Fig.5 Normalized Transient Response

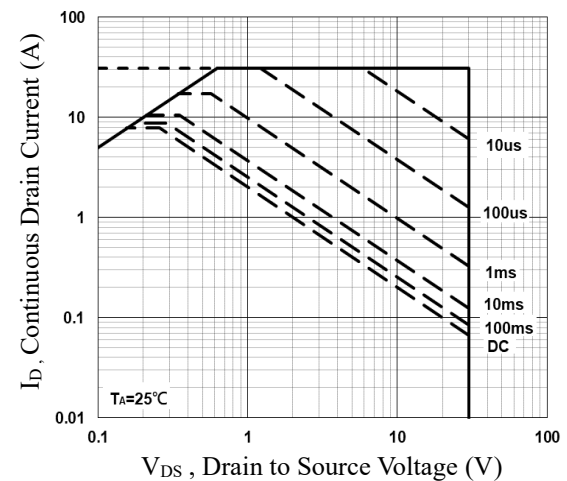


Fig.6 Maximum Safe Operation Area



Characteristics Curves

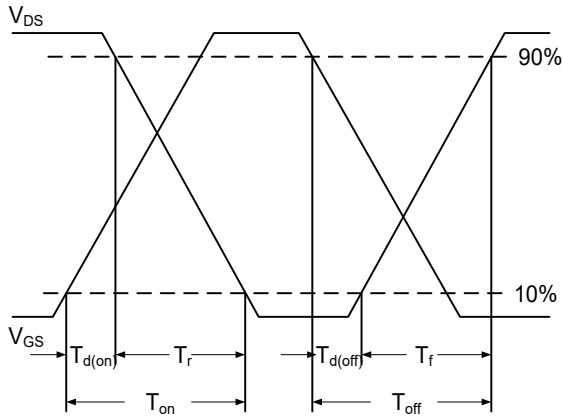
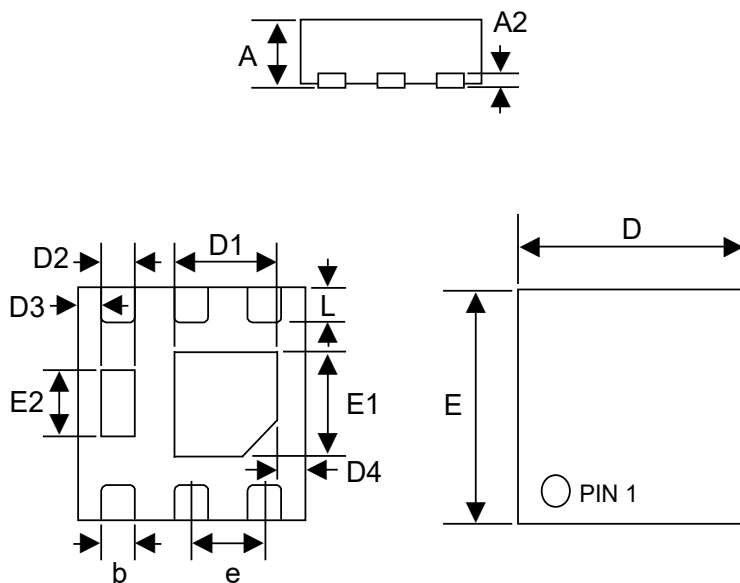


Fig.7 Switching Time Waveform

Package Outline Dimensions



Symbol	Dimensions in mm		Dimensions in inches	
	Min.	Max.	Min.	Max.
A	0.50	0.80	0.019	0.032
A2	0.152 REF		0.006 REF	
b	0.25	0.35	0.009	0.014
D	1.90	2.10	0.074	0.083
D1	0.80	1.00	0.031	0.040
D2	0.25	0.35	0.009	0.014
D3	0.20 BSC		0.008 BSC	
D4	0.25 BSC		0.010 BSC	
E	1.90	2.10	0.074	0.083
E1	0.80	1.10	0.031	0.044
E2	0.46	0.66	0.018	0.260
e	0.65 BSC		0.026 BSC	
L	0.25	0.35	0.009	0.014

DFN2x2-6L



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